



Industrial Cooperation for Microsystems / Microelectronic Packaging

Joint Workshop
Promoting Joint Laboratory IZM / Todai JoiLIT
Fraunhofer IZM
The University of Tokyo

In cooperation with Fraunhofer
Representative Office Japan and NPO
EcoDesign Promotion Network

February 20, 2003
9:00 - 20:00
Hilton Tokyo
Room Kikuen, 4F



Fraunhofer Gesellschaft



東京大学

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- Venue** **Hotel Hilton Tokyo**
Room Kikuen, 4F
6-6-2 Nishi-Shinjuku
Shinjuku-ku, Tokyo 160-0023
Tel. 03-3344-5111
- Access** [www.hilton.co.jp/Japan/HiltonTokyo/Access/
Access_Index.asp](http://www.hilton.co.jp/Japan/HiltonTokyo/Access/Access_Index.asp)

Fraunhofer IZM – The University of Tokyo
Joint Workshop “Industrial Cooperation for Microsystems/
Microelectronic Packaging”
on Thursday, February 20, 2003, Hilton Tokyo

Name

Organization

Address

Tel

Fax

E-Mail

to The University of Tokyo
Prof. Dr. Tadatomo Suga

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Industrial Cooperation for Microsystems / Microelectronic Packaging

Reliability, Quality and Sustainability

Joint Workshop of the **Fraunhofer Institute for Reliability and Microintegration (IZM)** and **The University of Tokyo**

Promoting Joint Laboratory IZM / Todai JoiLIT

Chairs: Prof. Dr. Tadatomo Suga, Dr. Lorenz Granrath

09.00 Opening Address

Dr. Hiroaki Koshibu

Director, NPO EcoDesign Promotion Network

Prof. Takashi Nanya

Director, RCAST, The University of Tokyo

Prof. Dr. Herbert Reichl

Director of the Fraunhofer Institute for Reliability and Microintegration IZM, Director of Research Center for Microperipheric Technologies, Technical University of Berlin

09.45 RESEARCH AND DEVELOPMENT SERVICES – OFFERS FOR JAPANESE INDUSTRY –

**Organization of the Cooperation FhG/IZM –
University of Tokyo: Collaborative Offers of
JoiLIT**

Prof. Dr. Tadatomo Suga

The University of Tokyo, RCAST

**MEMS devices Fabricated Using Advanced
Micromachining**

Prof. Dr. T. Gessner, Head of Department Micro
Devices and Equipment, Fraunhofer IZM

**Integration of Passives in Wafer Level
Packaging CSP's**

K. Scherpinski, Department High Density Inter-
connect and Wafer Level Packaging, Fraunhofer IZM

**Stacking of Thinned Chips for Various
Technological Applications**

Dr. A. Klumpp, Department Vertical System
Integration, Fraunhofer IZM-M

**EcoDesign Needs for European (International)
Markets**

O. Deubzer, Department Environmental Engineering,
Fraunhofer IZM

12.00 Lunch Break

13.30 RESEARCH AND DEVELOPMENT SERVICES – OFFERS FOR THE JAPANESE INDUSTRY –

**Integration of Passive and Active Components
into Build-up Layers**

R. Aschenbrenner, Head of Department of Chip
Interconnection Technologies and Vice Director,
Fraunhofer IZM

**Flip Chip Solutions Using Electroplated AuSn
Solder Bumps**

M. Hutter, Department of Chip Interconnection
Technologies, Fraunhofer IZM

**Electrical Optical Circuit Board (EOCB) –
Photonic Packaging on PCB Level**

Dr. H. Schroeder, Department Board Interconnection
Technologies, Fraunhofer IZM

**Microdeformation Analysis Using Digital Image
Correlation Tools: "microDAC and nanoDAC"**

Dr. D. Vogel, Department Mechanical Reliability and
Micro Materials, Fraunhofer IZM

Enabling Technologies for "Electronic Grains"

J. Wolf, Department High Density Interconnect and
Wafer Level Packaging, Fraunhofer IZM

15.45 Break

16.00 SUCCESSFUL MANAGEMENT OF CONTRACT RESEARCH AND DEVELOPMENT

Managing Applied R&D Efficiently

L. Stobbe, Department Environmental Engineering,
Fraunhofer IZM / **H. Griese**, Head of Department
Environmental Engineering, Fraunhofer IZM

Best Practices, References

R. Aschenbrenner, Vice Director Fraunhofer IZM

Contract Management Procedures

M. Richter, Head of Administration, Fraunhofer IZM

Fraunhofer Representative Office Tokyo

Dr. L. Granrath, Representative Industrial
Technology, Fraunhofer Representative Office Japan

17.00 Reception